**[0005]** New molded polyimide insulating article having low dielectric constant and high flexural modulus is developed.

**[0006]** In one aspect, the disclosure is directed to a molded insulating polyimide article formed from a composition comprising

(A) at least one polyimide, and

(B) 30 to 70 weight % of at least one sheet silicate, based on the weight of the polyimide composition,

wherein the dielectric constant of the molded insulating polyimide article is lower than 5 and the flexural modulus of the molded insulating polyimide article is at least 7.5 GPa.

## DETAILED DESCRIPTION

**[0007]** Polyimides used in the composition may contain the characteristic -CO- R-CO- group as a linear or heterocyclic unit along the main chain of the polymer backbone. The polyimide can be obtained, for example, from the reaction of monomers such as an organic tetracarboxylic acid, or the corresponding anhydride or ester derivative thereof, with an aliphatic or aromatic diamine.

**[0008]** A polyimide precursor as used to prepare a polyimide is an organic polymer that becomes the corresponding polyimide when the polyimide precursor is heated or chemically treated. In certain embodiments of the thus-obtained polyimide, about 60 to 100 mole percent, preferably about 70 mole percent or more, more preferably about 80 mole percent or more, of the repeating units of the polymer chain thereof has a polyimide structure as represented, for example, by the following formula:

